

RADIAL HEAT SINK WITH HELICAL SHAPED FINS

Abstract of the Disclosure

5 An electronic assembly includes an integrated circuit (e.g., a processor)
mounted on a substrate (e.g., a motherboard), and a radial heat sink thermally coupled
to the integrated circuit. The radial heat sink includes a core having an outer surface,
and a plurality of helical fins that extend from the outer surface of the core. The
electronic assembly may include a fan positioned near the heat sink. The appropriate
10 angle for the helical fins relative to the longitudinal axis of the heat sink depends in
part on the direction of the airflow that is produced by the fan.

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